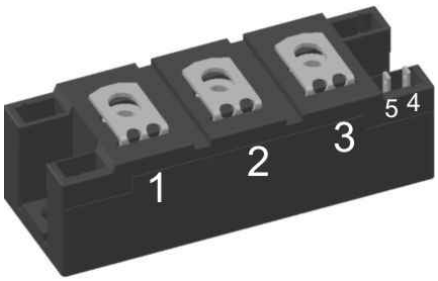
Thyristor Module

V_{RRM} = 2x 1600 V
I_{TAV} = 130 A
V_T = 1.08 V

Phase leg

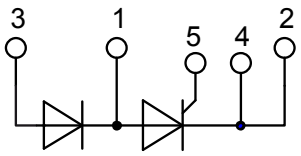
Part number

MCD132-16io1



Backside: isolated

E72873



Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability
- Direct Copper Bonded Al2O3-ceramic

Applications:

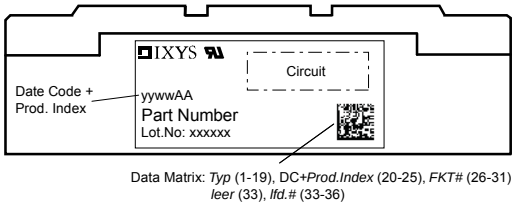
- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: Y4

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

Rectifier				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
$V_{RSM/DSM}$	*max. non-repetitive reverse/forward blocking voltage*		T_{VJ} = 25°C			1700	V
$V_{RRM/DRM}$	*max. repetitive reverse/forward blocking voltage*		T_{VJ} = 25°C			1600	V
$I_{R/D}$	*reverse current, drain current*	$V_{R/D}$ = 1600 V	T_{VJ} = 25°C			200	µA
		$V_{R/D}$ = 1600 V	T_{VJ} = 125°C			10	mA
V_T	*forward voltage drop*	I_T = 150 A	T_{VJ} = 25°C			1.14	V
		I_T = 300 A				1.36	V
		I_T = 150 A	T_{VJ} = 125°C			1.08	V
		I_T = 300 A				1.36	V
I_{TAV}	*average forward current*	T_C = 85°C	T_{VJ} = 125°C			130	A
$I_{T(RMS)}$	*RMS forward current*	180° sine				300	A
V_{T0}	*threshold voltage* } *for power loss calculation only*		T_{VJ} = 125°C			0.80	V
r_T	*slope resistance* }					1.5	mΩ
R_{thJC}	*thermal resistance junction to case*					0.23	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.10		K/W
P_{tot}	*total power dissipation*		T_C = 25°C			435	W
I_{TSM}	*max. forward surge current*	t = 10 ms; (50 Hz), sine	T_{VJ} = 45°C			4.75	kA
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			5.13	kA
		t = 10 ms; (50 Hz), sine	T_{VJ} = 125°C			4.04	kA
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			4.36	kA
I^2t	*value for fusing*	t = 10 ms; (50 Hz), sine	T_{VJ} = 45°C			112.8	kA²s
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			109.5	kA²s
		t = 10 ms; (50 Hz), sine	T_{VJ} = 125°C			81.6	kA²s
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			79.1	kA²s
C_J	*junction capacitance*	V_R = 400 V f = 1 MHz	T_{VJ} = 25°C		211		pF
P_{GM}	*max. gate power dissipation*	t_P = 30 µs	T_C = 125°C			120	W
		t_P = 500 µs				60	W
P_{GAV}	*average gate power dissipation*					8	W
$(di/dt)_{cr}$	*critical rate of rise of current*	T_{VJ} = 125°C; f = 50 Hz repetitive,	I_T = 500 A			150	A/µs
		t_P = 200 µs; di_G/dt = 0.5 A/µs;					
		I_G = 0.5A; V_D = ⅔ V_{DRM} non-repet.,	I_T = 160 A			500	A/µs
$(dv/dt)_{cr}$	*critical rate of rise of voltage*	V_D = ⅔ V_{DRM}	T_{VJ} = 125°C			1000	V/µs
		R_{GK} = ∞; method 1 (linear voltage rise)					
V_{GT}	*gate trigger voltage*	V_D = 6 V	T_{VJ} = 25°C			2.5	V
			T_{VJ} = -40°C			2.6	V
I_{GT}	*gate trigger current*	V_D = 6 V	T_{VJ} = 25°C			150	mA
			T_{VJ} = -40°C			200	mA
V_{GD}	*gate non-trigger voltage*	V_D = ⅔ V_{DRM}	T_{VJ} = 125°C			0.2	V
I_{GD}	*gate non-trigger current*					10	mA
I_L	*latching current*	t_p = 30 µs	T_{VJ} = 25°C			300	mA
		I_G = 0.5A; di_G/dt = 0.5 A/µs					
I_H	*holding current*	V_D = 6 V R_{GK} = ∞	T_{VJ} = 25°C			200	mA
t_{gd}	*gate controlled delay time*	V_D = ½ V_{DRM}	T_{VJ} = 25°C			2	µs
		I_G = 0.5A; di_G/dt = 0.5 A/µs					
t_q	*turn-off time*	V_R = 100 V; I_T = 160 A; V_D = ⅔ V_{DRM}	T_{VJ} = 125°C		150		µs
		di/dt = 10 A/µs; dv/dt = 20 V/µs; t_p = 200 µs					

Package Y4					Ratings			
Symbol	Definition	Conditions			min.	typ.	max.	Unit
I_{RMS}	*RMS current*	per terminal					300	A
T_{VJ}	*virtual junction temperature*				-40		125	°C
T_{op}	*operation temperature*				-40		100	°C
T_{stg}	*storage temperature*				-40		125	°C
Weight						150		g
M_D	*mounting torque*				2.25		2.75	Nm
M_T	*terminal torque*				4.5		5.5	Nm
$d_{Spp/App}$	*creepage distance on surface | striking distance through air*		*terminal to terminal*	14.0	10.0			mm
$d_{Spb/Apb}$			*terminal to backside*	16.0	16.0			mm
V_{ISOL}	*isolation voltage*	t = 1 second	50/60 Hz, RMS; I_{ISOL} ≤ 1 mA		3600			V
		t = 1 minute			3000			V

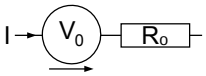


Data Matrix: *Typ* (1-19), DC+*Prod.Index* (20-25), *FKT#* (26-31)
leer (33), *lfd.#* (33-36)

Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MCD132-16io1	MCD132-16io1	Box	6	430625

Equivalent Circuits for Simulation

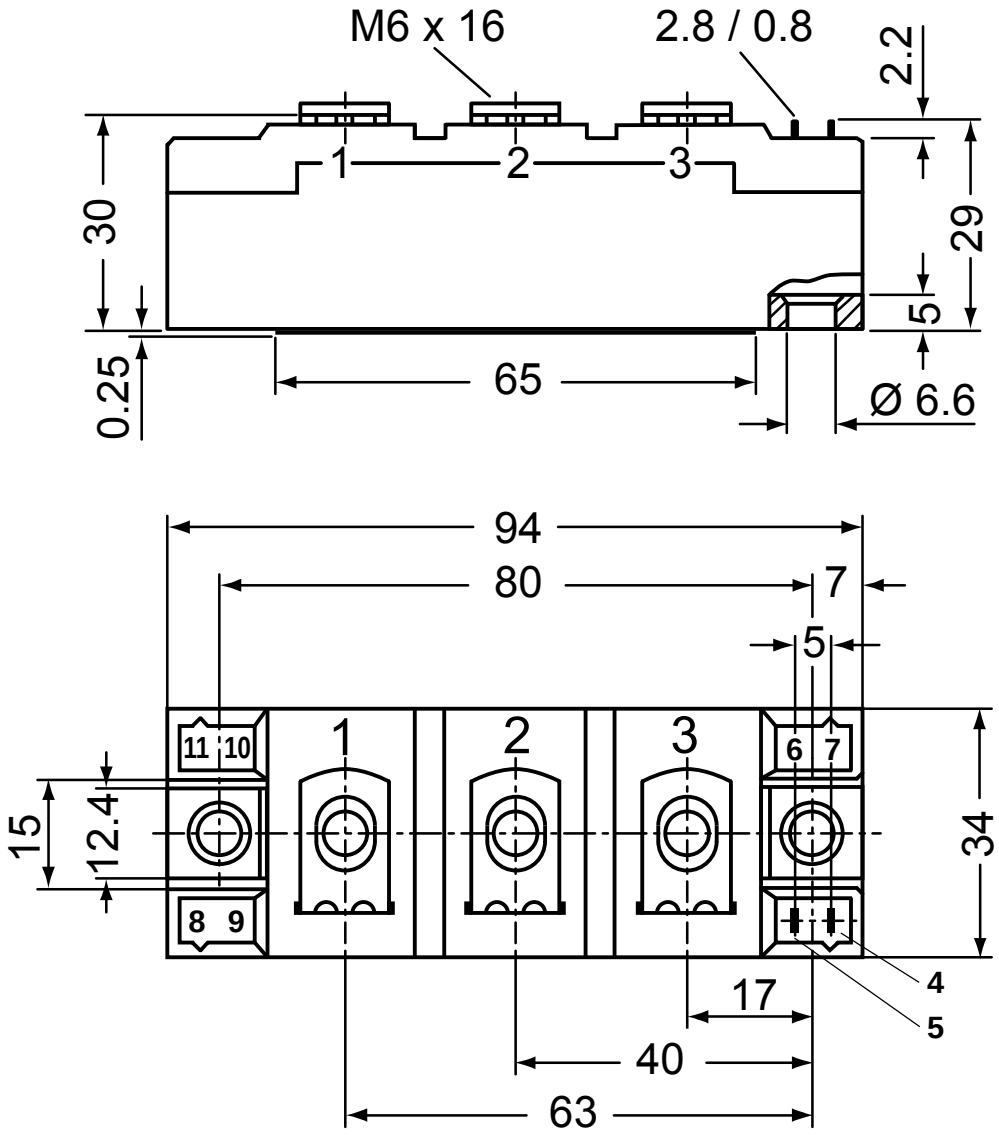
** on die level* T_{VJ} = 125 °C



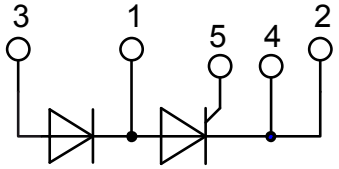
Thyristor

$V_{0\,max}$	*threshold voltage*	0.8	V
$R_{0\,max}$	*slope resistance **	0.8	mΩ

Outlines Y4



Optional accessories for modules
Keyed gate/cathode twin plugs with wire length = 350 mm, gate = white, cathode = red
Type ZY 180L (L = Left for pin pair 4/5)
Type ZY 180R (R = Right for pin pair 6/7)
} UL 758, style 3751



Thyristor

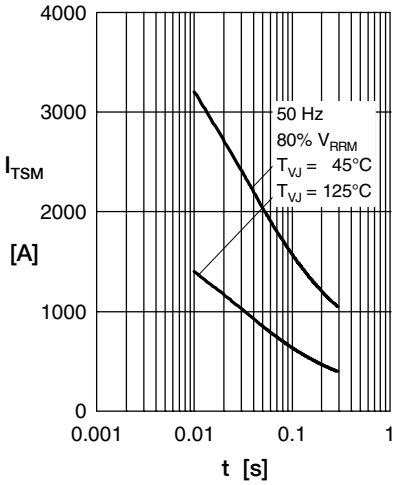


Fig. 1 Surge overload current I_{TSM}, I_{FSM}: Crest value, t: duration

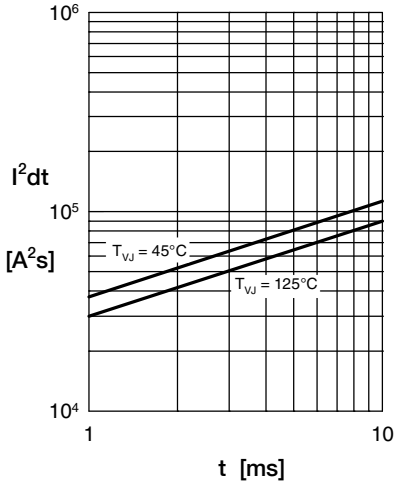


Fig. 2 I^2t versus time (1-10 ms)

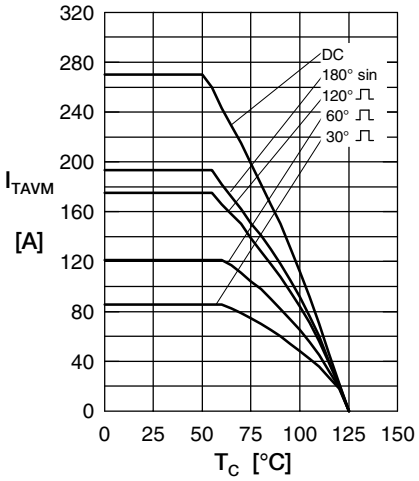


Fig. 3 Max. forward current at case temperature

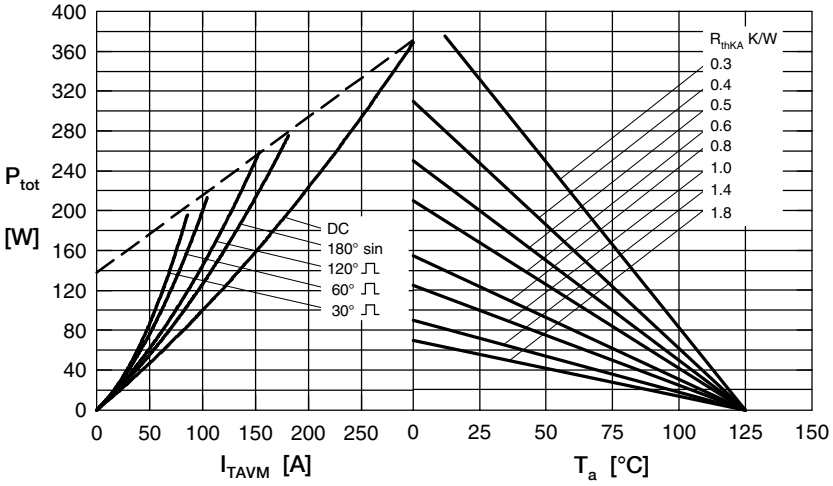


Fig. 4 Power dissipation vs. on-state current & ambient temperature (per thyristor or diode)

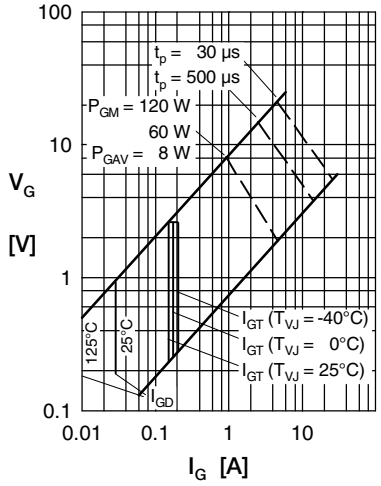


Fig. 5 Gate trigger characteristics

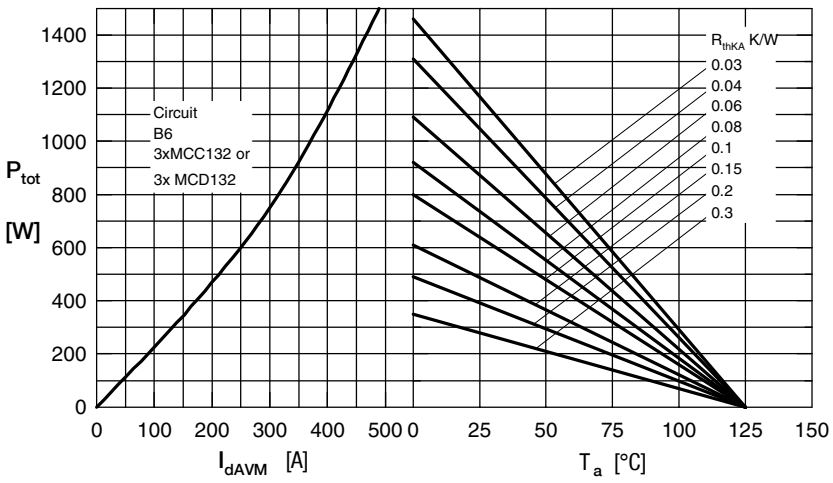


Fig. 6 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

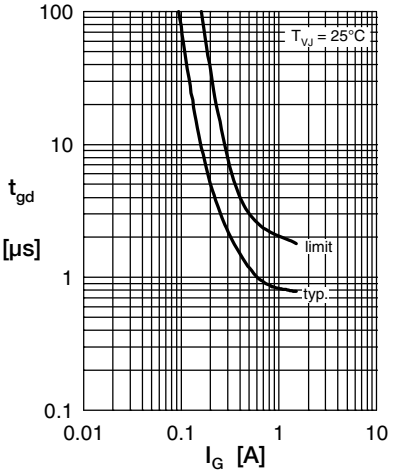


Fig. 7 Gate trigger delay time

Rectifier

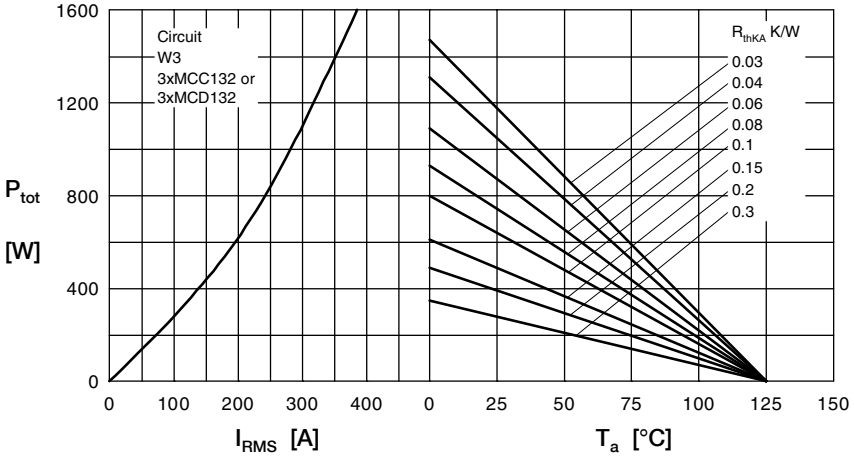


Fig. 8 Three phase AC-controller: Power dissipation versus RMS output current and ambient temperature

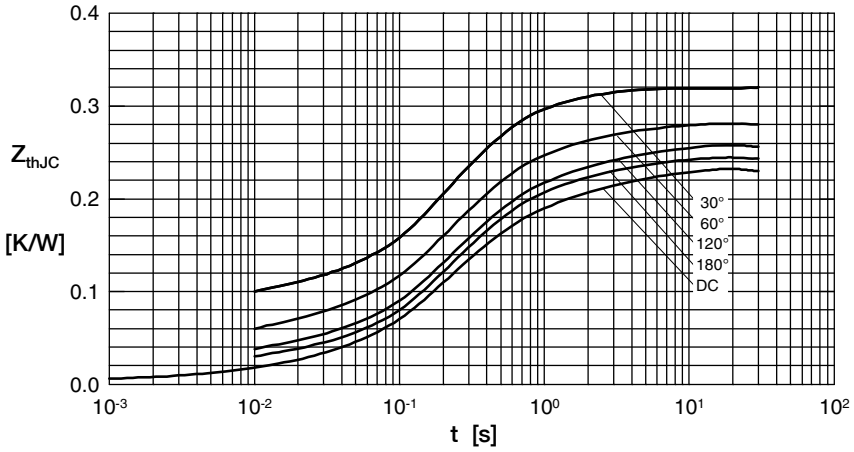


Fig. 9 Transient thermal impedance junction to case (per thyristor/diode)

R_{thJC} for various conduction angles d:

d	R_{thJC} [K/W]
DC	0.230
180°	0.244
120°	0.255
60°	0.283
30°	0.321

Constants for Z_{thJC} calculation:

i	R_{thi} [K/W]	t_i [s]
1	0.0095	0.001
2	0.0175	0.065
3	0.2030	0.400

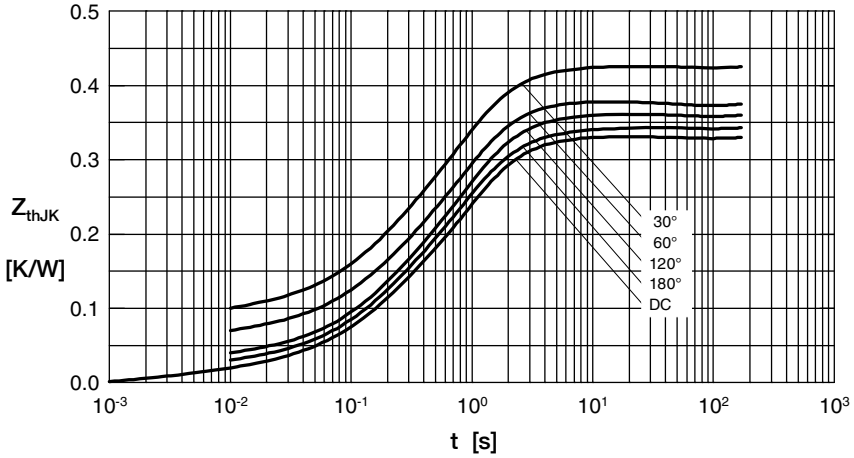


Fig. 10 Transient thermal impedance junction to heatsink (per thyristor/diode)

R_{thJK} for various conduction angles d:

d	R_{thJK} [K/W]
DC	0.330
180°	0.344
120°	0.355
60°	0.383
30°	0.421

Constants for Z_{thJK} calculation:

i	R_{thi} [K/W]	t_i [s]
1	0.0095	0.001
2	0.0175	0.065
3	0.2030	0.400
4	0.1000	1.290